

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS2502	Jun-97	9721 A6	CARSEM	DM708155ACB	1.2μ OX/NI EPROM	08 SOIC 150

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Preconditioning (P/C):
HTC Vapor Phase
P-19854

<u>Electrical</u>	<u>Cum %</u>
234/10	4.3%
F1	

Infant / High Voltage Life
125°C, 7.0 V.
P-20013, P-20065

<u>0 Hr</u>	<u>48 Hr</u>	<u>336 Hr</u>	<u>1KHr</u>	<u>*Failure Rate</u>
224/2	210/0	75/0	75/0	31 Fits
Write Data				
F2				

*Chi Squared Method, 60% C. L., 55°C & 5.5V; Temperature Derating: Ea = 0.7 ev; Voltage Derating B = 1.0

Temp Cycle
-55°C to +125°C
P-20066

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
30/0	30/0	0.0%

Biased Moisture
85°C/85% RH, 5.5 V.
P-20067

<u>274 Hr</u>	<u>959 Hr</u>	<u>Cum %</u>
75/0	75/0	0.0%

Storage Life
150°C, No bias
P-20068

<u>336 Hr</u>	<u>1KHr</u>	<u>Cum %</u>
30/0	30/0	0.0%

Failure Mode

F1: 10-Multiple modes
F2: 2-Would not program

Failure Analysis

F1 & F2 - Lot was misprobed in that 2 of 4 (quad site) load board connectors were reversed. In addition, the lot missed the final test steps. Corrective actions: the load board was modified to a single connector. An electronic lot tracking system was implemented to prevent future lots from being routed past the final test step.